

Appl. No. 10/711,795  
Amdt. dated February 22, 2006  
Reply to Office action of January 10, 2006

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in this application:

**Listing of Claims:**

- 1 (currently amended): A multi-layered printed circuit board (PCB) comprising:  
5       a plastic substrate containing a plurality of layers; and  
      a circuit layout formed on at least one layer of the plastic substrate, the circuit layout  
      having a first layout and a second layout,  
      wherein the second layout comprises a pseudo-layout to prevent the PCB from being  
      bent when heated.
- 10       2 (original): The PCB of claim 1 wherein density of circuits of the second layout has a  
      lower circuit density than that of the first layout.
- 15       3 (previously presented): The PCB of claim 1 wherein the circuit layout comprises signal  
      traces and power traces, and the pseudo-layout is isolated from the signal traces and  
      the power traces on the PCB.
- 20       4 (original): The PCB of claim 1 wherein the pseudo-layout comprises a plurality of  
      pseudo-traces neither for power nor signal transmission.
- 5 (original): The PCB of claim 3 wherein the pseudo-traces are parallel to each other in a  
      netlike structure.
- 25       6 (previously presented): The PCB of claim 5 wherein the parallel pseudo-traces have an  
      interval distance of 5mil.
- 7 (original): The PCB of claim 5 wherein the width of the pseudo-traces is 5mil.

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8-13 (cancelled).